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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/668,745	09/23/2003	David W. Boggs	884.942US1 1789		
21186	7590 01/24/2006		EXAMINER		
SCHWEGM	AN, LUNDBERG, WOE	DINH, T	DINH, TUAN T		
1600 TCF TO	WER EIGHT STREET	ART UNIT	PAPER NUMBER		
MINNEAPOLIS, MN 55402			2841		
			DATE MAILED: 01/24/200	DATE MAILED: 01/24/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Applicat	ion No.	Applicant(s)					
Office Action Communication		10/668,	745	BOGGS ET AL.					
Office Action Summary			ər	Art Unit					
		Tuan T.		2841					
Period fo	The MAILING DATE of this communic or Reply	ation appears on ti	ne cover sheet with the c	correspondence add	dress				
WHIC - Exter after - If NC - Failu Any	ORTENED STATUTORY PERIOD FO CHEVER IS LONGER, FROM THE MA nsions of time may be available under the provisions of SIX (6) MONTHS from the mailing date of this community period for reply is specified above, the maximum stature to reply within the set or extended period for reply with the set or extended period for reply wit	ILING DATE OF T 37 CFR 1.136(a). In no e nication. tory period will apply and II, by statute, cause the ap	HIS COMMUNICATION vent, however, may a reply be tin will expire SIX (6) MONTHS from polication to become ABANDONE	N. nely filed the mailing date of this co D (35 U.S.C. § 133).					
Status					•				
1)🖂	Responsive to communication(s) filed	on 07 November	2005.						
/	This action is FINAL . 2b)⊠ This action is non-final.								
3)	,—								
	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.								
Dispositi	on of Claims								
4)⊠	4)⊠ Claim(s) <u>1-20 and 28-30</u> is/are pending in the application.								
	4a) Of the above claim(s) <u>17-20</u> is/are withdrawn from consideration.								
5)□	Claim(s) is/are allowed.								
6)⊠	Claim(s) <u>1-16 and 28-30</u> is/are rejected.								
7)	Claim(s) is/are objected to.								
8)[_	8) Claim(s) are subject to restriction and/or election requirement.								
Applicati	on Papers								
9) The specification is objected to by the Examiner.									
10)⊠ The drawing(s) filed on <u>09/23/03</u> is/are: a)□ accepted or b)⊠ objected to by the Examiner.									
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).									
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).									
11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.									
Priority ι	ınder 35 U.S.C. § 119								
12)☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a)☐ All b)☐ Some * c)☐ None of:									
	1. Certified copies of the priority documents have been received.								
	2. Certified copies of the priority documents have been received in Application No								
	3. Copies of the certified copies of the priority documents have been received in this National Stage								
	application from the Internationa	al Bureau (PCT Ru	ıle 17.2(a)).	•					
* See the attached detailed Office action for a list of the certified copies not received.									
Attachmen	· (s)								
1) Notic	e of References Cited (PTO-892)		4) Interview Summary	(PTO-413)					
	e of Draftsperson's Patent Drawing Review (PTC		Paper No(s)/Mail Da	ate	152\				
	nation Disclosure Statement(s) (PTO-1449 or PT · No(s)/Mail Date	O/SB/08)	5) Notice of Informal P 6) Other:	atent Application (P10	-192)				

DETAILED ACTION

1. Applicant's election without traverse of Group I, Specie I (claims 1-16, and 28-30) in the reply filed on 11/07/05 is acknowledged.

Drawings

2. The drawings are objected to under 37 CFR 1.83(a). The drawings must show every feature of the invention specified in the claims. Therefore, the "memory communicatively coupled to the processor (claim 10, line 3)" must be shown or the feature(s) canceled from the claim(s). No new matter should be entered.

Corrected drawing sheets in compliance with 37 CFR 1.121(d) are required in reply to the Office action to avoid abandonment of the application. Any amended replacement drawing sheet should include all of the figures appearing on the immediate prior version of the sheet, even if only one figure is being amended. The figure or figure number of an amended drawing should not be labeled as "amended." If a drawing figure is to be canceled, the appropriate figure must be removed from the replacement sheet, and where necessary, the remaining figures must be renumbered and appropriate changes made to the brief description of the several views of the drawings for consistency. Additional replacement sheets may be necessary to show the renumbering of the remaining figures. Each drawing sheet submitted after the filing date of an application must be labeled in the top margin as either "Replacement Sheet" or "New Sheet" pursuant to 37 CFR 1.121(d). If the changes are not accepted by the examiner,

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the applicant will be notified and informed of any required corrective action in the next Office action. The objection to the drawings will not be held in abeyance.

By applying art, the examiner assumes that claim 10, line 3 should be read - - a memory electrical communicatively to the processor - -.

Claim Objections

3. Claims 1, 5, 6, 10, and 29-30 are objected to because of the following informalities:

Claim 1, lines 7-8, change "a plurality of component mounting pads" to - - the plurality of component mounting pads - - for proper antecedence basis.

Claim 5, lines 2-3, change "a component mounting pads" to - - the component mounting pad - - for proper antecedence basis.

Claim 5, line 4, change, "a plurality of component mounting pads" to - - the plurality of component mounting pads - - for proper antecedence basis.

Claim 6, line 3, change "a component mounting pads" to - - the component mounting pads - - for proper antecedence basis.

Claim 6, lines 4-5, change "a plurality of component mounting pads" to - - the plurality of component mounting pads - - for proper antecedence basis.

Claim 10, line 11, change, "a plurality of component mounting pads" to - - the plurality of component mounting pads - - for proper antecedence basis.

Claims 29-30, line 1, "The device of claim 1" changed to - - The device of claim 28 - - for proper antecedence basis.

Appropriate correction is required.

Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 5. Claims 1-16, and 28-30 are rejected under 35 U.S.C. 102(e) as being anticipated by Brinthaupt, III et al. (U.S. Patent 6,521,842, hereafter Brinthaupt).

As to claims 1-4, 7-9, and 28-30, Brinthaupt discloses a device, which is a semiconductor chip having a multilayer circuit board (100, column 1, lines 61-62) as shown in figures 1-2 comprising:

first and second major exterior surfaces (top and bottom surfaces 106, 112, column 2, line 10), at least one of the first and second major exterior surfaces including a plurality of component mounting pads (105, column 1, line 63);

a plane metallization layer (a feature, which is a trace), which is power, ground, or reference voltage planes (121-132) within the device; a plated through hole or vias (110A-110C) attached to the plane metallization layer and terminating at the at least one of the first and second major exterior surfaces (106, 112) including the plurality of

component mounting pads (105), the plated through hole (110) attached to the plane metallization layer (121-132), and electrically isolated from the plurality of component mounting pads (105).

As to claim 5, Brinthaupt further comprising a signal carrying plated through hole which passes though the plane metallization layer (121-132) within the device (100) and terminates at the component mounting pad (105) at the at least one of the first and second major exterior surfaces including a plurality of component mounting pads (105).

As to claim 6, Brinthaupt discloses the signal carrying plated through hole which passes though the plane metallization layer (121-132) is electrically isolated from the plane metallization layer and is connected (electrical) to the component mounting pad at the at least one of the first and second major exterior surfaces including a plurality of component mounting pads (105).

As to claims 10-15, Brinthaupt discloses a system as shown in figures 1-2 comprising:

a processor and a memory (active components 160, column 1, line 34, column 2, line 31) are electrical communication; and

a device, which is a printed circuit board or a portion of a semiconductor chip (100) associated with at least one of the memory or the processor further including:

first and second major exterior surfaces (top and bottom surfaces 106, 112, column 2, line 10), at least one of the first and second major exterior surfaces including a plurality of component mounting pads (105, column 1, line 63); a plane metallization layer, which is power, ground, or reference voltage planes (121-132) within the device;

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a plated through hole or vias (110A-110C) attached to the plane metallization layer and terminating at the at least one of the first and second major exterior surfaces (106, 112) including the plurality of component mounting pads (105), the plated through hole (110) attached to the plane metallization layer (121-132), and electrically isolated from the plurality of component mounting pads (105).

As to claim 16, Brinthaupt discloses the signal carrying plated through hole which passes though the plane metallization layer (121-132) is electrically isolated from the plane metallization layer and is connected (electrical) to the component mounting pad at the at least one of the first and second major exterior surfaces including a plurality of component mounting pads (105).

Conclusion

6. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. McKiddy, Bhatt et al., Fang, Kwong et al., and Stoddard et al. disclose related art.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan T. Dinh whose telephone number is 571-272-1929. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kammie Cuneo can be reached on 571-272-1957. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Tuan Dinh

January 16, 2006.